

What is claimed is:

1. A chip for use in a voice communication device comprising:
  - a bone conduction sensing pattern disposed within the chip;
  - and
  - a microphone sensing pattern disposed within the chip.
2. The chip of claim 1 further comprising an integrated circuit portion interconnected to the bone conduction sensing pattern and the microphone sensing pattern.
3. The chip of claim 1 wherein the bone conduction sensing pattern is positioned on a first end of the chip, the first end opposite a second end of the chip, the microphone sensing pattern positioned on the second end of the chip.
4. A chip for use in a voice communication device comprising:
  - a substrate;
  - a piezoelectric polymer overlaying the substrate;
  - the piezoelectric polymer having a first pattern and a second pattern, the first pattern being an accelerometer sensor pattern and the second pattern being a microphone sensor pattern.
5. The chip of claim 4 further comprising an electronic sensor portion overlaying the substrate.
6. The chip of claim 5 wherein the electronic sensor portion includes a signal conditioning circuit.

7. The chip of claim 4 wherein the piezoelectric polymer is divided into a first portion and a second portion at opposite ends of the chip, the accelerometer sensor pattern defined within the first portion and the microphone sensor pattern defined within the second portion.

8. A voice communication device comprising:  
a chip having a microphone sensor and an accelerometer.

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